

Technical data Sheet

TCG Thermal Transfer Compound

DESCRIPTION

TCG is a heat transfer compound that is formulated with select polydimethyl siloxane fluid in combination with metallic oxide fillers to provide superior thermal conductivity.

APPLICATIONS

Designed for use as a heat transfer compound in both the electrical, and the electronic industries, TCG conforms to the guidelines outlined in military specification MIL C-47113B. Characterized by its high thermal conductivity, high dielectric constant, and high dissipation factor, TCG is an ideal material for use in thermocouple wells, power diodes, transistors, semi-conductors, ballasts among various other applications.

Physical Properties	Test Method	Value
Appearance		White Paste
Worked Penetration 60X	ASTM D 217	240-320
Bleed	200°C / 24 Hours	1.0 % Max
Evaporation	200°C / 24 Hours	2.0 % Max
Specific Gravity		2.6
Thermal Conductivity	Hot Wire Method	0.9 W/mK
Volume Resistivity	ASTM D 257	1.2 x 10 ⁻¹⁵ ohm / cm
Dissipation Factor	ASTM D 150	0.0074
Dielectric Constant	ASTM D 150	4.81
Dielectric strength	ASTM D 149	22 kV/mm
Operating temperature		-55 to + 220°C
Shelf Life		12 months @ 25°C

ADDITIONAL INFORMATION

Intek believes that the information provided is a true and accurate description of the typical characteristics of the aforementioned product; however, it is the responsibility of the individual user to thoroughly test the product in their specific application to determine performance.

Pack Sizes

30 CC Dispensing Barrels to suit our manual dispensing gun or EFD type timed dispensers
Larger packs include - 1, 5, or 25 Kilo Pails



30 CC Syringe with Manual Gun

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